

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: : Customer Number: 89518
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Mou-Shiung Lin : Confirmation Number: 8665
: :
Application No.: 10/755,042 : Group Art Unit: 2815
: :
Filed: January 9, 2004 : Examiner: Jackson Jr, Jerome
: :
For: INTEGRATED CHIP PACKAGE STRUCTURE USING SILICON SUBSTRATE AND
METHOD OF MANUFACTURING THE SAME

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF ELECTRONIC TRANSMISSION
I hereby certify that this correspondence is being electronically-
transmitted to the United States Patent and Trademark Office on
November 16, 2009
/Tobi A. Terry/

Tobi A. Terry

RESPONSE/AMENDMENT

Sir:

In response to the Office Action dated June 16, 2009, the Applicant respectfully requests further examination of the above-identified application in light of the following:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Amendments to the Drawings begin on page 9 of this paper and include an attached replacement sheet.

Remarks/Arguments begin on page 10 of this paper.

A Replacement Sheet including amended drawings figures is attached following page 17 of this paper.